



OPA343 OPA2343 OPA4343

www.ti.com

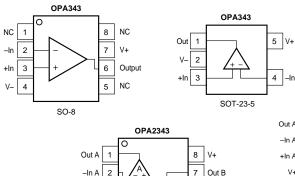
SINGLE-SUPPLY, RAIL-TO-RAIL OPERATIONAL AMPLIFIERS *microAmplifier*™ Series

FEATURES

- RAIL-TO-RAIL INPUT/OUTPUT
- MICRO SIZE PACKAGES
- WIDE BANDWIDTH: 5.5MHz
 HIGH SLEW RATE: 6V/µs
- LOW THD+NOISE: 0.0007% (f = 1kHz) ● LOW QUIESCENT CURRENT: 850µA/chan ● SINGLE, DUAL, AND QUAD VERSIONS

DESCRIPTION

OPA343 series rail-to-rail CMOS operational amplifiers are designed for low-cost, miniature applications. They are optimized for low-voltage, single-supply operation. Rail-to-rail input/output and high-speed operation make them ideal for driving sampling Analog-to-Digital (A/D) converters. They are also well suited for general-purpose and audio applications as well as providing I/V conversion at the output of Digital-to-Analog (D/A) converters. Single, dual, and quad versions have identical specifications for design flexibility.



SO-8, MSOP-8

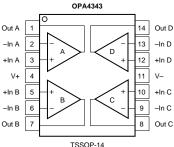
–In B

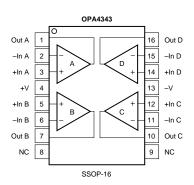
APPLICATIONS

- DRIVING A/D CONVERTERS
- PCMCIA CARDS
- **DATA ACQUISITION**
- AUDIO PROCESSING
- COMMUNICATIONS
- ACTIVE FILTERS
- TEST EQUIPMENT

The OPA343 series operates on a single supply as low as 2.5V, and input common-mode voltage range extends 500mV beyond the supply rails. Output voltage swings to within 1mV of the supply rails with a 100k Ω load. They offer excellent dynamic response (BW = 5.5MHz, SR = 6V/ μ s), yet quiescent current is only 850 μ A. Dual and quad designs feature completely independent circuitry for lowest crosstalk and freedom from interaction.

The single (OPA343) packages are the tiny SOT-23-5 surface mount and SO-8 surface mount. The dual (OPA2343) comes in the miniature MSOP-8 surface mount and SO-8 surface mount. The quad (OPA4343) packages are the space-saving SSOP-16 surface mount, SO-14 surface mount, and TSSOP-14 surface mount. All are specified from -40°C to +85°C and operate from -55°C to +125°C. A SPICE macromodel is available for design analysis.







SPECIFICATIONS: $V_S = 2.7V$ to 5.5V

Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+85^{\circ}C$. $V_S = 5V$.

At T_A = +25°C, R_L = 10k Ω connected to $V_S/2$ and V_{OUT} = $V_S/2$, unless otherwise noted.

			O			
PARAMETER		CONDITION	MIN	TYP ⁽¹⁾	MAX	UNITS
OFFSET VOLTAGE Input Offset Voltage vs Temperature vs Power Supply Over Temperature Channel Separation, dc	V _{os} dV _{os} /dT PSRR	$V_S = 5V$ $V_S = 2.7V \text{ to } 5.5V, V_{CM} = 0V$ $V_S = 2.7V \text{ to } 5.5V, V_{CM} = 0V$		±2 ±3 40	±8 200 200	mV μV/°C μV/V μV/V
INPUT BIAS CURRENT Input Bias Current Over Temperature Input Offset Current	I _B			±0.2 ±0.2	±10 ± 60 ±10	pA pA pA
NOISE Input Voltage Noise, f = 0.1 to 50kH. Input Voltage Noise Density, f = 1kH Current Noise Density, f = 1kHz				8 25 3		μVrms nV/√Hz fA/√Hz
INPUT VOLTAGE RANGE Common-Mode Voltage Range Common-Mode Rejection Ratio	V _{CM} CMRR	$-0.3V < V_{CM} < (V+) - 1.8V$ $V_S = 5V, -0.3V < V_{CM} < 5.3V$ $V_S = 2.7V, -0.3V < V_{CM} < 3V$	-0.3 74 60 54	92 75 70	(V+) + 0.3	V dB dB dB
INPUT IMPEDANCE Differential Common-Mode				10 ¹³ 3 10 ¹³ 6		Ω pF Ω pF
OPEN-LOOP GAIN Open-Loop Voltage Gain Over Temperature Over Temperature	A _{OL}	$\begin{split} R_L &= 100 k \Omega, \ 5 m V < V_O < (V+) - 5 m V \\ R_L &= 100 k \Omega, \ 5 m V < V_O < (V+) - 5 m V \\ R_L &= 10 k \Omega, \ 50 m V < V_O < (V+) - 50 m V \\ R_L &= 10 k \Omega, \ 50 m V < V_O < (V+) - 50 m V \end{split}$	100 100 100 100	120 117		dB dB dB dB
Over Temperature		$R_L = 2k\Omega$, 200mV < V_O < (V+) - 200mV $R_L = 2k\Omega$, 200mV < V_O < (V+) - 200mV	92 92	110		dB dB
FREQUENCY RESPONSE Gain-Bandwidth Product Slew Rate Settling Time, 0.1% 0.01% Overload Recovery Time Total Harmonic Distortion + Noise	GBW SR THD+N	$G = 1 \\ V_S = 5V, G = 1, C_L = 100pF \\ V_S = 5V, 2V Step, C_L = 100pF \\ V_S = 5V, 2V Step, C_L = 100pF \\ V_{IN} \bullet G = V_S \\ V_S = 5V, V_O = 3Vp-p^{(2)}, G = 1, f = 1kHz$		5.5 6 1 1.6 0.2 0.0007		MHz V/μs μs μs μs κ
OUTPUT Voltage Output Swing from Rail ⁽³⁾ Over Temperature Over Temperature Over Temperature Short-Circuit Current	I _{sc}	$\begin{split} R_L &= 100k\Omega,\ A_{OL} \geq 100dB \\ R_L &= 100k\Omega,\ A_{OL} \geq 100dB \\ R_L &= 10k\Omega,\ A_{OL} \geq 100dB \\ R_L &= 10k\Omega,\ A_{OL} \geq 100dB \\ R_L &= 2k\Omega,\ A_{OL} \geq 92dB \\ R_L &= 2k\Omega,\ A_{OL} \geq 92dB \end{split}$		1 10 40 ±50	5 5 50 50 200 200	mV mV mV mV mV mA
Capacitive Load Drive POWER SUPPLY Specified Voltage Range Operating Voltage Range Quiescent Current (per amplifier) Over Temperature	V _S	$I_{O} = 0$, $V_{S} = +5V$ $I_{O} = 0$, $V_{S} = +5V$	2.7	2.5 to 5.5 0.85	5 1.25 1.4	V V mA mA
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance SOT-23-5 Surface Mount MSOP-8 Surface Mount	$ heta_{ extsf{JA}}$	5 . 5 .	-40 -55 -65	200 150	+85 +125 +150	°C/W °C/W °C/W
SO-8 Surface Mount SSOP-16 Surface Mount SO-14 Surface Mount TSSOP-14 Surface Mount				150 100 100 100 125		°C/W °C/W °C/W °C/W

NOTES: (1) $V_S = +5V$. (2) $V_{OUT} = 0.25V$ to 3.25V. (3) Output voltage swings are measured between the output and power supply rails.



ABSOLUTE MAXIMUM RATINGS(1)

Supply Voltage	7.5V
Signal Input Terminals, Voltage(2)	
Current ⁽²⁾	10mA
Output Short-Circuit(3)	Continuous
Operating Temperature	55°C to +125°C
Storage Temperature	65°C to +150°C
Junction Temperature	150°C
Lead Temperature (soldering, 10s)	300°C

NOTES: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. (2) Input terminals are diode-clamped to the power supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current-limited to 10mA or less. (3) Short-circuit to ground, one amplifier per package.



This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

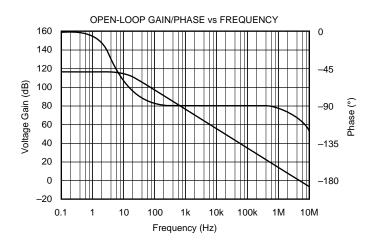
PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER ⁽¹⁾	TRANSPORT MEDIA
Single OPA343NA	5-Lead SOT-23-5	331	-40°C to +85°C	B43	OPA343NA/250 OPA343NA/3K	Tape and Reel Tape and Reel
OPA343UA "	SO-8 Surface-Mount	182 "	−40°C to +85°C	OPA343UA "	OPA343UA OPA343UA/2K5	Rails Tape and Reel
Dual						
OPA2343EA	MSOP-8 Surface-Mount	337	-40°C to +85°C	C43	OPA2343EA/250 OPA2343EA/2K5	Tape and Reel Tape and Reel
OPA2343UA "	SO-8 Surface-Mount	182 "	-40°C to +85°C	OPA2343UA "	OPA2343UA OPA2343UA/2K5	Rails Tape and Reel
Quad						
OPA4343EA	SSOP-16 Surface-Mount	322 "	-40°C to +85°C	OPA4343EA "	OPA4343EA/250 OPA4343EA/2K5	Tape and Reel Tape and Reel
OPA4343UA	SO-14 Surfac-Mount	235 "	-40°C to +85°C	OPA4343UA "	OPA4343UA OPA4343UA/2K5	Rails Tape and Reel
OPA4343NA	TSSOP-14 Surface-Mount	357 "	-40°C to +85°C	OPA4343NA "	OPA4343NA/250 OPA4343NA/2K5	Tape and Reel Tape and Reel

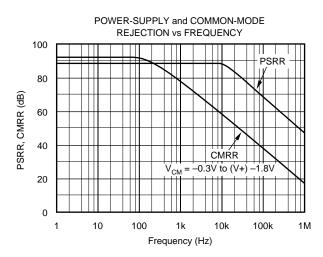
NOTE: (1) Models with a slash (/) are available only in Tape and Reel in the quantities indicated (e.g., /2K5 indicates 2500 devices per reel). Ordering 2500 pieces of "OPA2343EA/2K5" will get a single 2500 piece Tape and Reel.

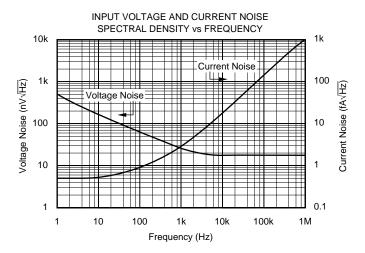
The information provided herein is believed to be reliable; however, BURR-BROWN assumes no responsibility for inaccuracies or omissions. BURR-BROWN assumes no responsibility for the use of this information, and all use of such information shall be entirely at the user's own risk. Prices and specifications are subject to change without notice. No patent rights or licenses to any of the circuits described herein are implied or granted to any third party. BURR-BROWN does not authorize or warrant any BURR-BROWN product for use in life support devices and/or systems.

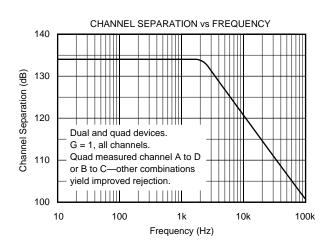


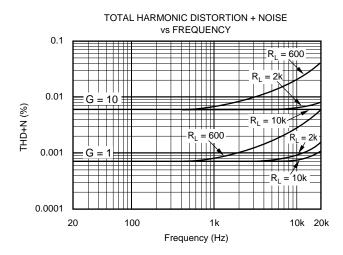
TYPICAL PERFORMANCE CURVES

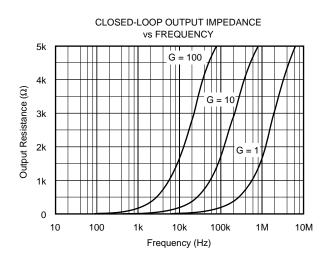






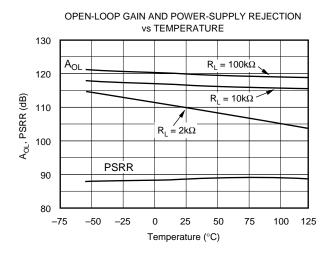


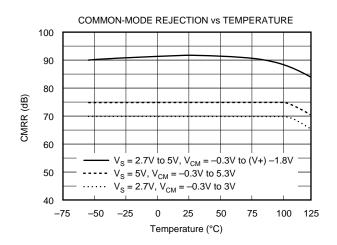


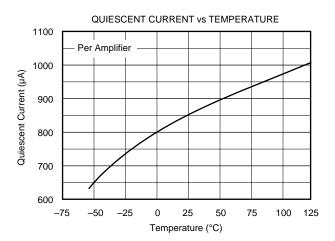


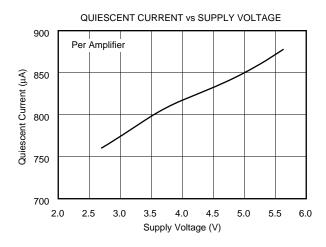


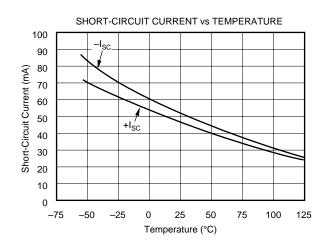
TYPICAL PERFORMANCE CURVES (Cont.)

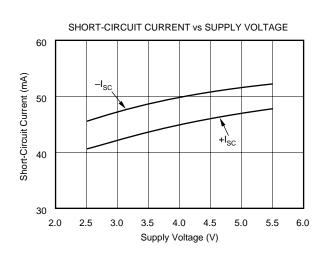






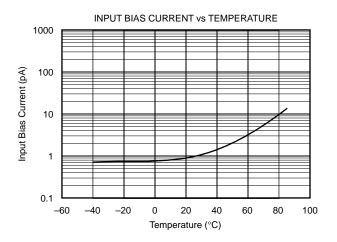


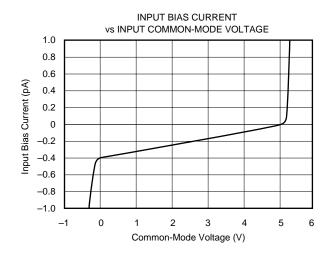


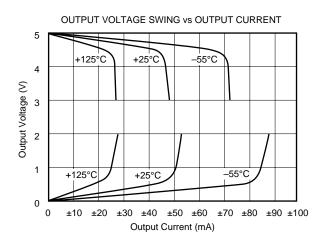


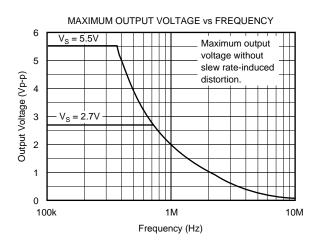


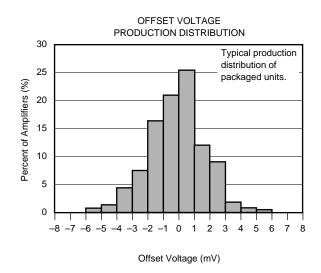
TYPICAL PERFORMANCE CURVES (Cont.)

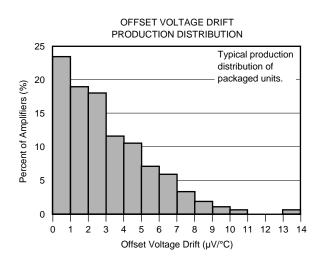






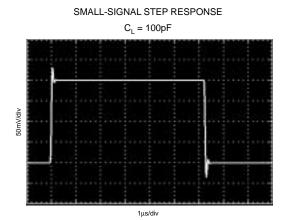


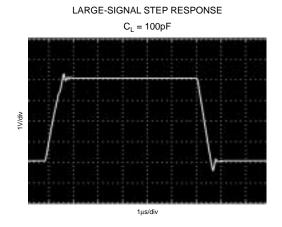


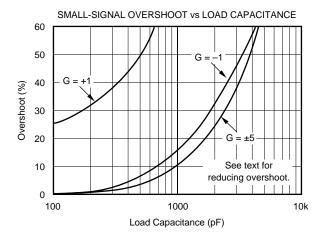


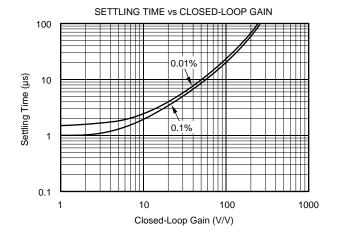


TYPICAL PERFORMANCE CURVES (Cont.)











APPLICATIONS INFORMATION

OPA343 series op amps are fabricated on a state-of-the-art 0.6 micron CMOS process. They are unity-gain stable and suitable for a wide range of general-purpose applications. Rail-to-rail input/output make them ideal for driving sampling A/D converters. In addition, excellent ac performance makes them well-suited for audio applications. The class AB output stage is capable of driving 600Ω loads connected to any point between V+ and ground.

Rail-to-rail input and output swing significantly increases dynamic range, especially in low-supply applications. Figure 1 shows the input and output waveforms for the OPA343 in unity-gain configuration. Operation is from a single +5V supply with a $10k\Omega$ load connected to $V_S/2$. The input is a 5Vp-p sinusoid. Output voltage is approximately 4.98Vp-p.

Power-supply pins should be bypassed with $0.01\mu F$ ceramic capacitors.

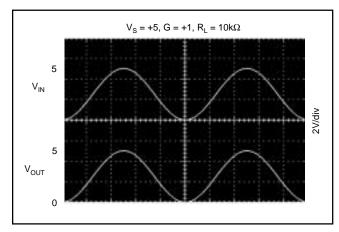


FIGURE 1. Rail-to-Rail Input and Output.

OPERATING VOLTAGE

OPA343 series op amps are fully specified from +2.7V to +5V. However, supply voltage may range from +2.5V to +5.5V. Parameters are guaranteed over the specified supply range—a unique feature of the OPA343 series. In addition, many specifications apply from -40°C to +85°C. Most behavior remains virtually unchanged throughout the full operating voltage range. Parameters which vary significantly with operating voltages or temperature are shown in the Typical Performance Curves.

RAIL-TO-RAIL INPUT

The input common-mode voltage range of the OPA343 series extends 500mV beyond the supply rails. This is achieved with a complementary input stage—an N-channel input differential pair in parallel with a P-channel differential pair, as shown in Figure 2. The N-channel pair is active for input voltages close to the positive rail, typically (V+) - 1.3V to 500mV above the positive supply. The P-channel pair is on for inputs from 500mV below the negative supply to approximately (V+) - 1.3V.

There is a small transition region, typically (V+) - 1.5V to (V+) - 1.1V, in which both input pairs are on. This 400mV transition region can vary ± 300 mV with process variation. Thus, the transition region (both stages on) can range from (V+) - 1.8V to (V+) - 1.4V on the low end, up to (V+) - 1.2V to (V+) - 0.8V on the high end. Within the 400mV transition region PSRR, CMRR, offset voltage, offset drift, and THD may be degraded compared to operation outside this region.

A double-folded cascode adds the signal from the two input pairs and presents a differential signal to the class AB output stage. Normally, input bias current is approximately 200fA, however, input voltages exceeding the power supplies by

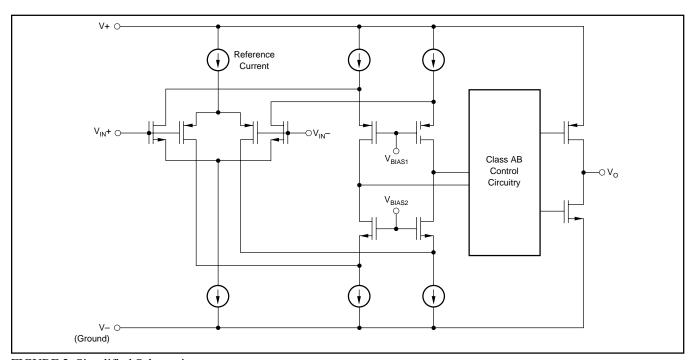


FIGURE 2. Simplified Schematic.



more than 500mV can cause excessive current to flow in or out of the input pins. Momentary voltages greater than 500mV beyond the power supply can be tolerated if the current on the input pins is limited to 10mA. This is easily accomplished with an input resistor, as shown in Figure 3. Many input signals are inherently current-limited to less than 10mA, therefore, a limiting resistor is not required.

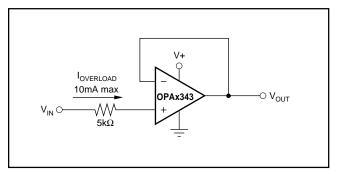


FIGURE 3. Input Current Protection for Voltages Exceeding the Supply Voltage.

RAIL-TO-RAIL OUTPUT

A class AB output stage with common-source transistors is used to achieve rail-to-rail output. For light resistive loads (>50k Ω), the output voltage is typically a few millivolts from the supply rails. With moderate resistive loads (2k Ω to 50k Ω), the output can swing to within a few tens of millivolts from the supply rails and maintain high open-loop gain. See the typical performanc curve "Output Voltage Swing vs Output Current."

CAPACITIVE LOAD AND STABILITY

OPA343 series op amps can drive a wide range of capacitive loads. However, all op amps under certain conditions may become unstable. Op amp configuration, gain, and load value are just a few of the factors to consider when determining stability. An op amp in unity gain configuration is the most susceptible to the effects of capacitive load. The

capacitive load reacts with the op amp's output resistance, along with any additional load resistance, to create a pole in the small-signal response which degrades the phase margin. In unity gain, OPA343 series op amps perform well, with a pure capacitive load up to approximately 1000pF. Increasing gain enhances the amplifier's ability to drive more capacitance. See the typical performance curve "Small-Signal Overshoot vs Capacitive Load."

One method of improving capacitive load drive in the unity gain configuration is to insert a 10Ω to 20Ω resistor in series with the output, as shown in Figure 4. This significantly reduces ringing with large capacitive loads. However, if there is a resistive load in parallel with the capacitive load, R_S creates a voltage divider. This introduces a dc error at the output and slightly reduces output swing. This error may be insignificant. For instance, with $R_L=10 k\Omega$ and $R_S=20\Omega$, there is only about a 0.2% error at the output.

DRIVING A/D CONVERTERS

OPA343 series op amps are optimized for driving medium speed (up to 100kHz) sampling A/D converters. However, they also offer excellent performance for higher-speed converters. The OPA343 series provides an effective means of buffering the A/D's input capacitance and resulting charge injection while providing signal gain. For applications requiring high accuracy, the OPA340 series is recommended.

Figures 5 and 6 show the OPA343 driving an ADS7816. The ADS7816 is a 12-bit, micro-power sampling converter in the tiny MSOP-8 package. When used with the miniature package options of the OPA343 series, the combination is ideal for space-limited and low-power applications. For further information consult the ADS7816 data sheet.

With the OPA343 in a noninverting configuration, an RC network at the amplifier's output can be used to filter high frequency noise in the signal (see Figure 5). In the inverting configuration, filtering may be accomplished with a capacitor across the feedback resistor (see Figure 6).

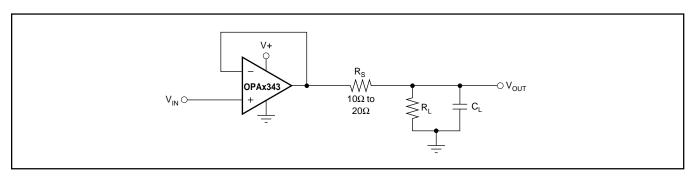


FIGURE 4. Series Resistor in Unity-Gain Configuration Improves Capacitive Load Drive.



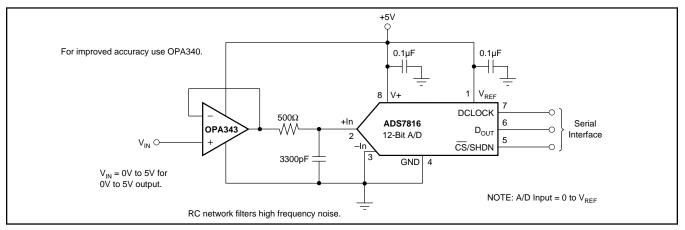


FIGURE 5. OPA343 in Noninverting Configuration Driving ADS7816.

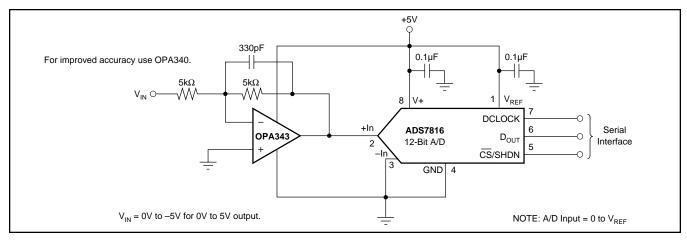


FIGURE 6. OPA343 in Inverting Configuration Driving ADS7816.

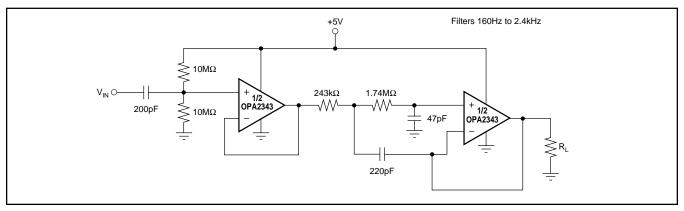


FIGURE 7. Speech Bandpass Filter.

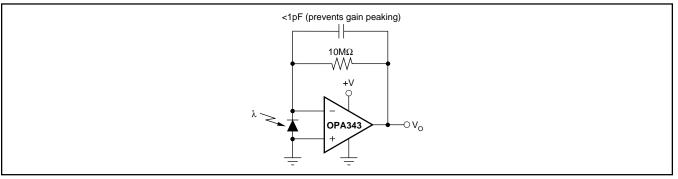


FIGURE 8. Transimpedance Amplifier.







10-Jun-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
OPA2343EA/250	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	C43	Samples
OPA2343EA/250G4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	C43	Samples
OPA2343EA/2K5	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	C43	Samples
OPA2343EA/2K5G4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	C43	Samples
OPA2343UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 2343UA	Samples
OPA2343UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 2343UA	Samples
OPA2343UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 2343UA	Samples
OPA2343UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 2343UA	Samples
OPA343NA/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	B43	Samples
OPA343NA/250G4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	B43	Samples
OPA343NA/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	B43	Samples
OPA343NA/3KG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	B43	Samples
OPA343UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 343UA	Samples
OPA343UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 343UA	Samples
OPA343UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 343UA	Samples
OPA343UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 343UA	Samples
OPA4343EA/250	ACTIVE	SSOP	DBQ	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 4343EA	Samples



www.ti.com

PACKAGE OPTION ADDENDUM

10-Jun-2014

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
OPA4343EA/250G4	ACTIVE	SSOP	DBQ	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 4343EA	Samples
OPA4343EA/2K5	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 4343EA	Samples
OPA4343EA/2K5G4	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 4343EA	Samples
OPA4343NA/250	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 4343NA	Samples
OPA4343NA/250G4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 4343NA	Samples
OPA4343NA/2K5	ACTIVE	TSSOP	PW	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA 4343NA	Samples
OPA4343UA	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA4343UA	Samples
OPA4343UA/2K5	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	OPA4343UA	Samples
OPA4343UAG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA4343UA	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL. Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

10-Jun-2014

- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Jul-2013

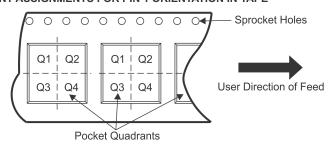
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2343EA/250	VSSOP	DGK	8	250	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2343EA/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2343UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA343NA/250	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
OPA343NA/3K	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
OPA343UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4343EA/250	SSOP	DBQ	16	250	180.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4343EA/2K5	SSOP	DBQ	16	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4343NA/250	TSSOP	PW	14	250	180.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
OPA4343NA/2K5	TSSOP	PW	14	2500	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
OPA4343UA/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

www.ti.com 24-Jul-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2343EA/250	VSSOP	DGK	8	250	366.0	364.0	50.0
OPA2343EA/2K5	VSSOP	DGK	8	2500	366.0	364.0	50.0
OPA2343UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA343NA/250	SOT-23	DBV	5	250	180.0	180.0	18.0
OPA343NA/3K	SOT-23	DBV	5	3000	180.0	180.0	18.0
OPA343UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA4343EA/250	SSOP	DBQ	16	250	210.0	185.0	35.0
OPA4343EA/2K5	SSOP	DBQ	16	2500	367.0	367.0	35.0
OPA4343NA/250	TSSOP	PW	14	250	210.0	185.0	35.0
OPA4343NA/2K5	TSSOP	PW	14	2500	367.0	367.0	35.0
OPA4343UA/2K5	SOIC	D	14	2500	367.0	367.0	38.0

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom Amplifiers amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers <u>microcontroller.ti.com</u> Video and Imaging <u>www.ti.com/video</u>

RFID <u>www.ti-rfid.com</u>

OMAP Applications Processors <u>www.ti.com/omap</u> TI E2E Community <u>e2e.ti.com</u>

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>